FLEXIBLE PIN LOCATION INTEGRATED CIRCUIT PACKAGE

ABSTRACT OF THE DISCLOSURE

An integrated circuit package (30) including a substrate (70) having an opening (86) and first and second surfaces(92, 94), a plurality of pads (100) disposed on the first and second surfaces (92, 94) having disposed thereon solder balls (150) electrically connected by a via (84) that provides the end-user with flexibility in the location of Pin #1 (96) is disclosed.

Figure 5